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A		<u> </u>			-					
E		FKN1WSJR-52 TP1 85Vac to 265Vac	1N4007 1000V	6.8μF	6 DRV C 5 CS G UCC28710D R4 243 0.5 Q1 STD3NK60ZD 600V	$\frac{1}{\sqrt{2}}$	R1 39.2k R3 11.0k 22pF D4 MURS160-13-F 600V	D1 1N4148W-7-F R2 150k E 150k E 150k E 150k	+ 05 - 186	• TP2
		TP3 •	D5 1N4007 1000V	400V	450V				25V	TP4
	PCB Number: PMP9530 PCB Rev: B	PCB LOGO Texas Instruments	nents and/or its licensors d is design will meet the sp of warrant that the doces	lo not warrant the acco	uracy or completeness of this specification table for your application or fit for any part You should completely validate and test y	or any information contained therei cular purpose, or will operate in an ur design	n. Texas Instruments and/ implementation. Texas Ins	for its licensors do not struments and/or its	Number: PMP9530 SVN Rev: Not in ve Dravm By: S Yu Engineer: Externer	Rev: A

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 SVN Rev: Not in version control provide the system functionality for your application.

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_ <b>●</b> TP2 18V/300mA	В
−● TP4	С
Designed for: Public Release       Mod. Date: 12/19/2013         Project Title: UCC28710 High-side Buck Converter       Image: Converter         Rev: A       Sheet Title: 85Vac- 265Vac to 18V/0.3A         ion control       Assembly Variant: 001         File: PMP9087 01.SchDoc       Size: B         of project lead Contact: http://www.ti.com/support       © Texas Instruments 2013         5       6	D

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